



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB025N10N3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000801086						
<b>Package</b>		PG-TO263-7-3		<b>Weight*</b>		1530.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.455	1.01	1.01	10096	10096
leadframe	non noble metal	iron	7439-89-6	0.909	0.06		594	
	inorganic material	phosphorus	7723-14-0	0.273	0.02		178	
	non noble metal	copper	7440-50-8	907.924	59.31	59.39	593105	593877
wire	non noble metal	aluminium	7429-90-5	15.190	0.99	0.99	9923	9923
encapsulation	organic material	carbon black	1333-86-4	8.540	0.56		5579	
	plastics	epoxy resin	-	93.944	6.14		61369	
	inorganic material	silicondioxide	60676-86-0	466.875	30.50	37.20	304988	371936
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	8046	8046
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	176
solder	noble metal	silver	7440-22-4	0.228	0.01		149	
	non noble metal	tin	7440-31-5	0.182	0.01		119	
	non noble metal	lead	7439-92-1	8.692	0.57	0.59	5678	5946
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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